RELIABILITY REPORT

FOR

MAX9916EKA+T

PLASTIC ENCAPSULATED DEVICES

April 14, 2015

MAXIM INTEGRATED

160 RIO ROBLES

SAN JOSE, CA 95134

Approved by
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Quality Assurance
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Conclusion

The MAX9916EKA+T successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The single MAX9914/MAX9915 and dual MAX9916/MAX9917 operational amplifiers feature maximized ratio of gain bandwidth to supply current and are ideal for battery-powered applications such as portable instrumentation, portable medical equipment, and wireless handsets. These CMOS op amps feature an ultra-low 1pA input bias current, rail-to-rail inputs and outputs, low 20µA supply current, and operate from a single 1.8V to 5.5V supply. For additional power conservation, the MAX9915/MAX9917 feature a low-power shutdown mode that reduces supply current to 1nA, and puts the amplifier outputs in a high-impedance state. These devices are unity-gain stable with a 1MHz gain-bandwidth product.

The MAX9914 and MAX9915 are available in 5-pin and 6-pin SC70 packages, respectively. The MAX9916 is available in an 8-pin SOT23 package, and the MAX9917 in a 10-pin µMAX® package. All devices are specified over the -40°C to +85°C extended operating temperature range.

II. Manufacturing Information

A. Description/Function:	1MHz, 20µA, Rail-to-Rail I/O Op Amps with Shutdown
B. Process:	C6Y
C. Number of Device Transistors:	312
D. Fabrication Location:	Japan
E. Assembly Location:	Malaysia, Thailand, Philippines
F. Date of Initial Production:	October 22, 2005

III. Packaging Information

A. Package Type:	8-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-0944
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	N/A
K. Single Layer Theta Jc:	800°C/W
L. Multi Layer Theta Ja:	196°C/W
M. Multi Layer Theta Jc:	70°C/W

IV. Die Information

A. Dimensions:	81X25 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.6 microns (as drawn)
F. Minimum Metal Spacing:	0.6 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% for all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 48 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 22.9 \times 10^{-9}$

$\lambda = 22.9$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maximintegrated.com/qa/reliability/monitor. Cumulative monitor data for the C6Y Process results in a FIT Rate of 0.17 @ 25C and 2.89 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot SPG3BU003B, 0539)

The OY17-3 die type has been found to have all pins able to withstand a transient pulse of:

ESD-HBM:	+/- 2500V per JEDEC JESD22-A114
ESD-CDM:	+/-750V per JEDEC JESD22-C101

Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX9916EKA+T

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	48	0	SPG0BU003A, D/C 0540

Note 1: Life Test Data may represent plastic DIP qualification lots.